# Electronic Version v1.1 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

### **CONVEYING PARTY DATA**

Name	Execution Date
Yoshitaka Aoki	08/30/2006
Keiichi Tsutsui	08/31/2006
Hirotaka Nishizawa	08/24/2006
Takashi Totsuka	08/24/2006

#### **RECEIVING PARTY DATA**

Name:	Sony Corporation	
Street Address:	7-35, Kitashinagawa 6-chome	
Internal Address:	Shinagawa-ku	
City:	Tokyo	
State/Country:	JAPAN	

Name:	Renesas Technology Corp.	
Street Address:	4-1, Marunouchi 2-chome	
Internal Address:	Chiyoda-ku	
City:	Tokyo	
State/Country:	JAPAN	

#### PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	11487812

## CORRESPONDENCE DATA

Fax Number: (312)441-0570

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Phone: 3122772006

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Correspondent Name: Robert J. Depke

Address Line 1: Rockey, Depke, Lyons & Kitzinger, LLC

PATENT REEL: 018387 FRAME: 0576

500164133

Address Line 2: Suite 5450, Sears Tower
Address Line 4: Chicago, ILLINOIS 60606-6306

ATTORNEY DOCKET NUMBER: 075834.00858

NAME OF SUBMITTER: Robert J. Depke

Total Attachments: 4
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source=858 Assignment#page4.tif

	Docket Number: <u>075834.00858</u>
ASSIGNMENT	
WHEREAS, I, as a below named inventor, residing at the addre only one name is listed below) or a joint inventor (if plural names are listed below	
CARD TRAY	
for which an application for Letters Patent of the United States of America was ename and address;	executed by me on the date indicated next to my
AND WHEREAS, Sony Corporation, a Japanese corporation Shinagawa-Ku, Tokyo, Japan and Renesas Technology, Corp., a Japanese corporation Chiyoda-ku, Tokyo, Japan (hereinafter referenced as ASSIGNEE) is desirous invention, said application disclosing the invention and in, to and under any Letter granted therefor in the United States and in any and all foreign countries;	oration with offices at 4-1, Marunouchi 2-chome, of acquiring all interest in, to and under said
NOW THEREFORE, in consideration of the sum of One consideration, the receipt and sufficiency of which are hereby acknowledged, I, a hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assign invention, said application, including any divisions and continuations as well as an to any and all Letters Patent of the United States, and countries foreign thereto, and to any and all priority rights and/or convention rights under the Internation Property, Inter-American Convention Relating to Patents, Designs and Industrial to which the United States of America adheres, and to any other benefits accruin applications for patents or securing of patents in the United States and countriequest the Commissioner of Patents to issue the said United States Letters Patent right, title and interest thereto;	is a sole or joint inventor as indicated below, do as, the entire right, title and interest in the said by reissues and reexaminations thereof, and in and which may be granted for said invention, and in anal Convention for the Protection of Industrial Models, and any other international agreements g or to accrue to me with respect to the filing of the ies foreign thereto, and I hereby authorize and
And I further agree to execute all necessary or desirable and la favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns m further remuneration, in order to perfect title in said invention, modifications, and Letters Patent of the United States and countries foreign thereto;	ay from time-to-time present to me and without
And I further agree to properly execute and deliver and without and lawful papers for application for foreign patents, for filing subdivisions of said reissue or reissues of any Letters Patent which may be granted for my afores hereafter require and prepare at its own expense;	application for patent, and or, for obtaining any
And I further agree that ASSIGNEE will, upon its request, be documents relating to said application, said invention and said Letters Patent and known and accessible to me and will testify as to the same in any interference or lit	l legal equivalents in foreign countries as may be
And I hereby covenant that no assignment, sale, agreement or e into which would conflict with this assignment and sale.	ncumbrance has been or will be made or entered
And I hereby authorize and request my attorney(s) of record is filing date of this application in the spaces that follow:	n this application to insert the serial number and
Application No. <u>11/487,812</u> Filing Dat	e:July 17, 2006
This assignment executed on the dates indicated below.	
Yoshitaka AOKI	
Name of first or sole inventor	Execution date of U.S. Patent Application
Kanagawa, Japan	
Residence of first or sole inventor	
Yorkitaka Joki	August 30, 2006
Signa Wire of First or sole inventor	Date of this Assignment

Keiichi TSUTSUI Name of second inventor	Execution date of U.S. Patent Application
Kanagawa, Japan Residence of second inventor	
Keiichi Tsutsui Signature of second inventor	August 31, 2006  Date of this Assignment
Signature of second inventor	Date of this Assignment
Hirotaka NISHIZAWA Name of third inventor	Execution date of U.S. Patent Application
Tokyo, Japan Residence of third inventor	
Signature of third inventor	Date of this Assignment
Takashi TOTSUKA Name of fourth inventor	Execution date of U.S. Patent Application
Tokyo, Japan Residence of fourth inventor	
Signature of fourth inventor	Date of this Assignment
Name of fifth inventor	Execution date of U.S. Patent Application
Residence of fifth inventor	
Signature of fifth inventor	Date of this Assignment
Name of sixth inventor	Execution date of U.S. Patent Application
Residence of sixth inventor	
Signature of sixth inventor	Date of this Assignment
Name of seventh inventor	Execution date of U.S. Patent Application
Residence of seventh inventor	·
Signature of seventh inventor	Date of this Assignment

Docket Number: <u>075834.00858</u> ASSIGNMENT
WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor (i only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in
CARD TRAY
for which an application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;
AND WHEREAS, Sony Corporation, a Japanese corporation with offices at 7-35, Kitashinagawa 6-Chome Shinagawa-Ku, Tokyo, Japan and Renesas Technology, Corp., a Japanese corporation with offices at 4-1, Marunouchi 2-chome Chiyoda-ku, Tokyo, Japan (hereinafter referenced as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;
NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, the entire right, title and interest in the said invention, said application, including any divisions and continuations as well as any reissues and reexaminations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;
And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;
And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;
And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;
And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.
And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow:
Application No. 11/487,812 Filing Date: July 17, 2006
This assignment executed on the dates indicated below.
Yoshitaka AOKI
Name of first or sole inventor Execution date of U.S. Patent Application
Kanagawa, Japan Residence of first or sole inventor
residence of first of sole inventor

Signature of First or sole inventor

PATENT REEL: 018387 FRAME: 0580

Date of this Assignment

Keiichi TSUTSUI	
Name of second inventor	Execution date of U.S. Patent Application
Kanagawa, Japan	- Ppicadon
Residence of second inventor	
Signature	
Signature of second inventor	Date of this Assignment
Hirotaka NISHIZAWA	
Name of third inventor	
	Execution date of U.S. Patent Application
Tokyo, Japan Residence of third inventor	
Hirotaka Vishizawa Signature of third inventor	24 Aug. 2006  Date of this Assignment
o-Santate of time inventor	Date of this Assignment
Takashi TOTSUKA	
Name of fourth inventor	Execution date of U.S. Patent Application
Tokyo, Japan	and a second aspine and it
Residence of fourth inventor	
Tahani Tatel	~ A A
Takashi Totsuka Signature of fourth inventor	24 Aug. 2006 Date of this Assignment
Name of fifth inventor	Execution date of U.S. Patent Application
Residence of fifth inventor	
signature of fifth inventor	Date of this Assignment
	Date of this Assignment
Name of sixth inventor	
·	Execution date of U.S. Patent Application
Lesidence of sixth inventor	
ignature of sixth inventor	Date of this Assignment
ame of seventh inventor	Execution date of U.S. Patent Application
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gnature of seventh inventor	Date of this Assignment

**RECORDED: 10/13/2006**